

PCN Number:	20181113000.1		PCN Date:	Nov 16, 2018									
Title:	Qualification of CDAT as an additional Assembly/Test site for select devices in the QFN package												
Customer Contact:	PCN Manager		Dept:	Quality Services									
Proposed 1st Ship Date:	Feb 16, 2019		Estimated Sample Availability:	Date Provided at Sample request									
Change Type:													
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site								
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material								
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process								
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site								
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials								
				<input type="checkbox"/>	Wafer Fab Process								
PCN Details													
Description of Change:													
<p>Texas Instruments is pleased to announce the qualification of CDAT as additional Assembly and Test Site for Select Devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th></th> <th>UTL1</th> <th>TI Clark (DRV6 Only)</th> <th>CDAT</th> </tr> </thead> <tbody> <tr> <td>Mount compound</td> <td>SID#PZ0031</td> <td>4207768</td> <td>4208625</td> </tr> </tbody> </table> <p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>							UTL1	TI Clark (DRV6 Only)	CDAT	Mount compound	SID#PZ0031	4207768	4208625
	UTL1	TI Clark (DRV6 Only)	CDAT										
Mount compound	SID#PZ0031	4207768	4208625										
Reason for Change:													
Continuity of Supply													
Anticipated impact on Material Declaration													
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.										
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):													
None													

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
UTAC	NSE	THA	Bangkok
TI Clark	QAB	PHL	Angeles City, Pampanga
CDAT	CDA	CHN	Chengdu

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 2d:

MSL '2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750



(Pb) E3

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

BQ24045DSQR	BQ24308DSGT	TPS2553DRVR-1	UCC27201ADRMT
BQ24045DSQT	TPS2552DRVR	TPS2553DRVT-1	UCC27201DRMR
BQ24308DSGR	TPS2552DRVT	UCC27201ADRMR	UCC27201DRMT



TI Information
Selective Disclosure

Qualification Report

Approve Date 12-Nov-2018

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: UCC27201ADRMR	QBS Package Reference: BQ24196RGER	QBS Package Reference: TPS2373-4	QBS Package Reference: TPS62140RGTR
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	3/231/0
FLAM	Flammability (UL 94V-0)	Method A/UL 94V-0	-	-	3/15/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-
HTOL	Life Test, 140C	480 Hours	-	-	1/77/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0	-
MSL	Thermal Path Integrity	Level 1-260C	3/36/0	-	-	-
MSL	Thermal Path Integrity	Level 2-260C	-	3/36/0	3/35/0	3/36/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
WBP	Bond Pull	Wires	3/228/0	3/228/0	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0	3/228/0	3/228/0

- QBS: Qual By Similarity
- Qual Device UCC27201ADRMR is qualified at LEVEL1-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com